

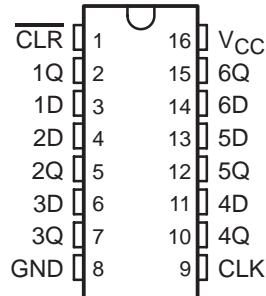
- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 14$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Contain Six Flip-Flops With Single-Rail Outputs
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators

description/ordering information

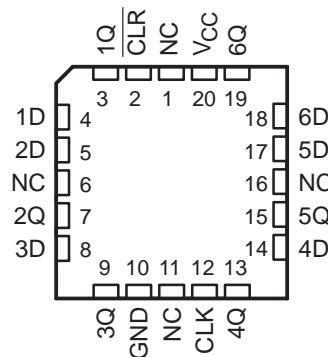
These positive-edge-triggered D-type flip-flops have a direct clear (CLR) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

SN54HC174 . . . J OR W PACKAGE
SN74HC174 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC174 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T _A	PACKAGE [†]	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC174N	SN74HC174N
	SOIC – D	Tube of 40	SN74HC174D	HC174
		Reel of 2500	SN74HC174DR	
		Reel of 250	SN74HC174DT	
	SOP – NS	Reel of 2000	SN74HC174NSR	HC174
	SSOP – DB	Reel of 2000	SN74HC174DBR	HC174
	TSSOP – PW	Tube of 90	SN74HC174PW	HC174
		Reel of 2000	SN74HC174PWR	
		Reel of 250	SN74HC174PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC174J	SNJ54HC174J
	CFP – W	Tube of 150	SNJ54HC174W	SNJ54HC174W
	LCCC – FK	Tube of 55	SNJ54HC174FK	SNJ54HC174FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

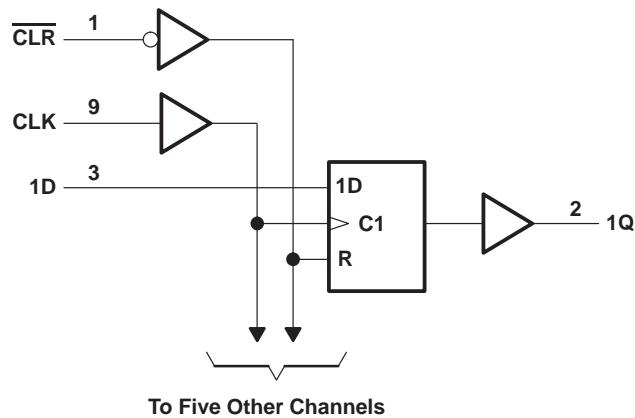
SN54HC174, SN74HC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR

SCLS119D – DECEMBER 1982 – REVISED SEPTEMBER 2003

FUNCTION TABLE (each flip-flop)

INPUTS			OUTPUT Q
CLR	CLK	D	
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	Q ₀

logic diagram (positive logic)



Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Storage temperature range, T_{stg} -65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC174			SN74HC174			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5		1.5				V
		V _{CC} = 4.5 V	3.15		3.15				
		V _{CC} = 6 V	4.2		4.2				
V _{IL}	Low-level input voltage	V _{CC} = 2 V		0.5		0.5			V
		V _{CC} = 4.5 V		1.35		1.35			
		V _{CC} = 6 V		1.8		1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/ΔV	Input transition rise/fall time	V _{CC} = 2 V		1000		1000			ns
		V _{CC} = 4.5 V		500		500			
		V _{CC} = 6 V		400		400			
T _A	Operating free-air temperature		-55	125	-40	85			°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			SN54HC174		SN74HC174		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 μA	2 V	1.9	1.998	1.9		1.9		V	
			4.5 V	4.4	4.499	4.4		4.4			
			6 V	5.9	5.999	5.9		5.9			
		I _{OH} = -4 mA	4.5 V	3.98	4.3	3.7		3.84			
			6 V	5.48	5.8	5.2		5.34			
		I _{OL} = 20 μA	2 V		0.002	0.1	0.1		0.1		
V _{OL}	V _I = V _{IH} or V _{IL}		4.5 V		0.001	0.1	0.1		0.1		
			6 V		0.001	0.1	0.1		0.1		
			I _{OL} = 4 mA	4.5 V		0.17	0.26	0.4	0.33		
			I _{OL} = 5.2 mA	6 V		0.15	0.26	0.4	0.33		
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100	±1000	±1000		nA		
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			8	160	80		μA		
C _i		2 V to 6 V		3	10	10	10		pF		

**SN54HC174, SN74HC174
HEX D-TYPE FLIP-FLOPS
WITH CLEAR**

SCLS119D – DECEMBER 1982 – REVISED SEPTEMBER 2003

timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC174		SN74HC174		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	6		4.2		5		MHz
		4.5 V		31		21		25	
		6 V		36		25		29	
t _w	Pulse duration	CLR low	2 V	80	120		100		ns
			4.5 V	16	24		20		
			6 V	14	20		17		
		CLK high or low	2 V	80	120		100		
			4.5 V	16	24		20		
			6 V	14	20		17		
t _{su}	Setup time before CLK↑	Data	2 V	100	150		125		ns
			4.5 V	20	30		25		
			6 V	17	25		21		
		CLR inactive	2 V	100	150		125		
			4.5 V	20	30		25		
			6 V	17	25		21		
t _h	Hold time, data after CLK↑	2 V	0		0		0		ns
		4.5 V	0		0		0		
		6 V	0		0		0		

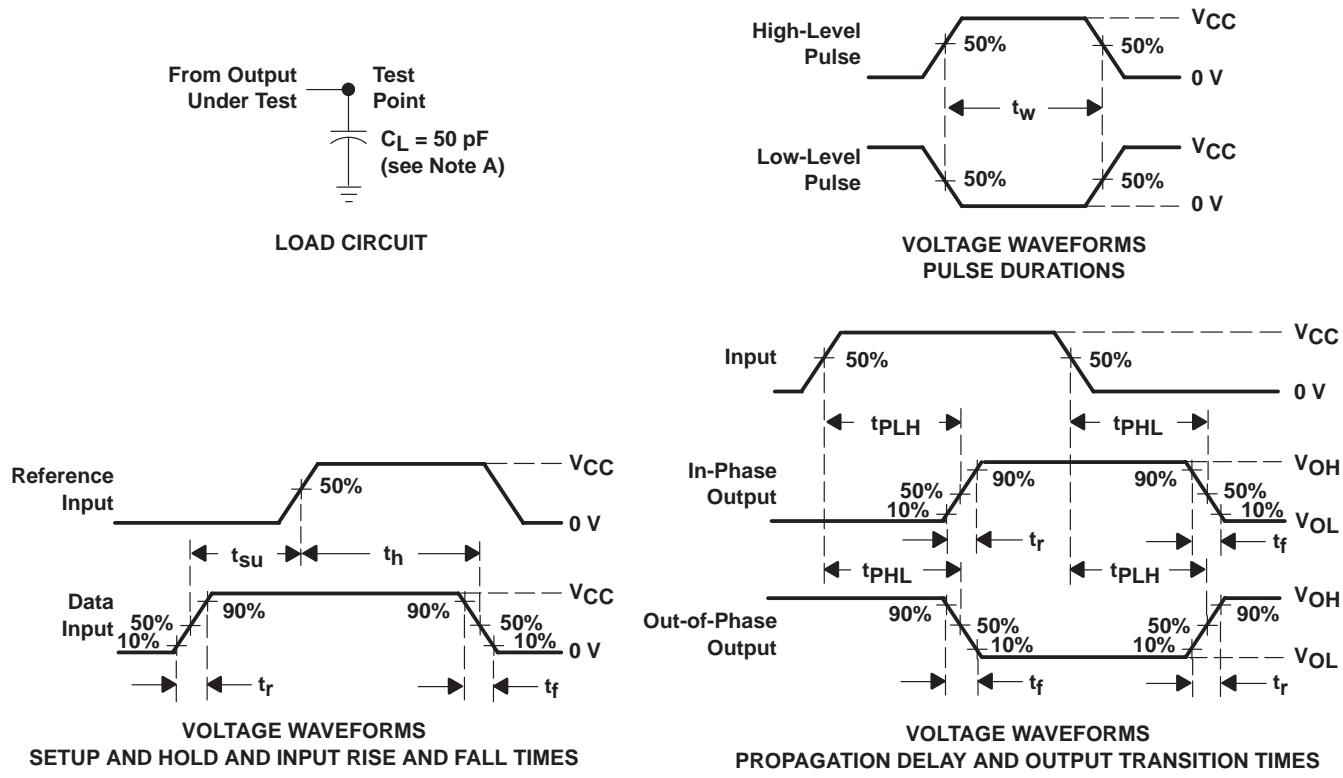
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	T _A = 25°C			SN54HC174		SN74HC174		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			2 V	6	9		4.2		5		MHz
			4.5 V	31	44		21		25		
			6 V	36	50		25		29		
t _{pd}	CLR	Any	2 V	58	160		240		200		ns
			4.5 V	17	32		48		40		
			6 V	14	27		41		34		
			2 V	58	160		240		200		
	CLK	Any	4.5 V	17	32		48		40		
			6 V	14	27		41		34		
			2 V	38	75		110		90		ns
			4.5 V	8	15		22		19		
			6 V	6	13		19		16		

operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance per flip-flop			No load	27	pF

PARAMETER MEASUREMENT INFORMATION



NOTES:

- C_L includes probe and test-fixture capacitance.
- Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, $Z_O = 50 \Omega$, $t_f = 6$ ns, $t_r = 6$ ns.
- For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- The outputs are measured one at a time with one input transition per measurement.
- t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
84073012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84073012A SNJ54HC 174FK	Samples
8407301EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407301EA SNJ54HC174J	Samples
8407301FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407301FA SNJ54HC174W	Samples
JM38510/65307BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65307BEA	Samples
M38510/65307BEA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510/ 65307BEA	Samples
SN54HC174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54HC174J	Samples
SN74HC174D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174DBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC174N	Samples
SN74HC174NE4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC174N	Samples
SN74HC174NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174PW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174PWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SN74HC174PWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC174	Samples
SNJ54HC174FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84073012A SNJ54HC	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
										174FK	
SNJ54HC174J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407301EA SNJ54HC174J	Samples
SNJ54HC174W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	8407301FA SNJ54HC174W	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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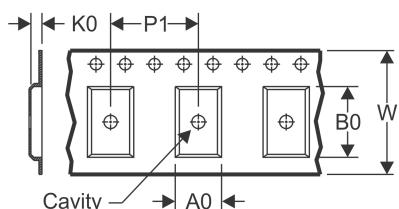
OTHER QUALIFIED VERSIONS OF SN54HC174, SN74HC174 :

- Catalog: [SN74HC174](#)
- Military: [SN54HC174](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

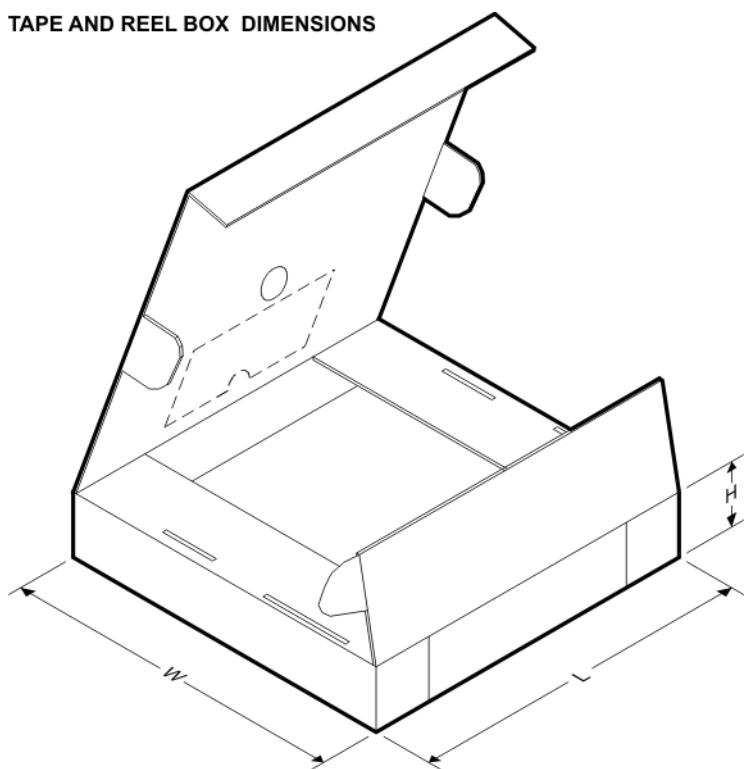
TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC174DR	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC174DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC174DRG4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC174NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC174PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC174PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC174PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


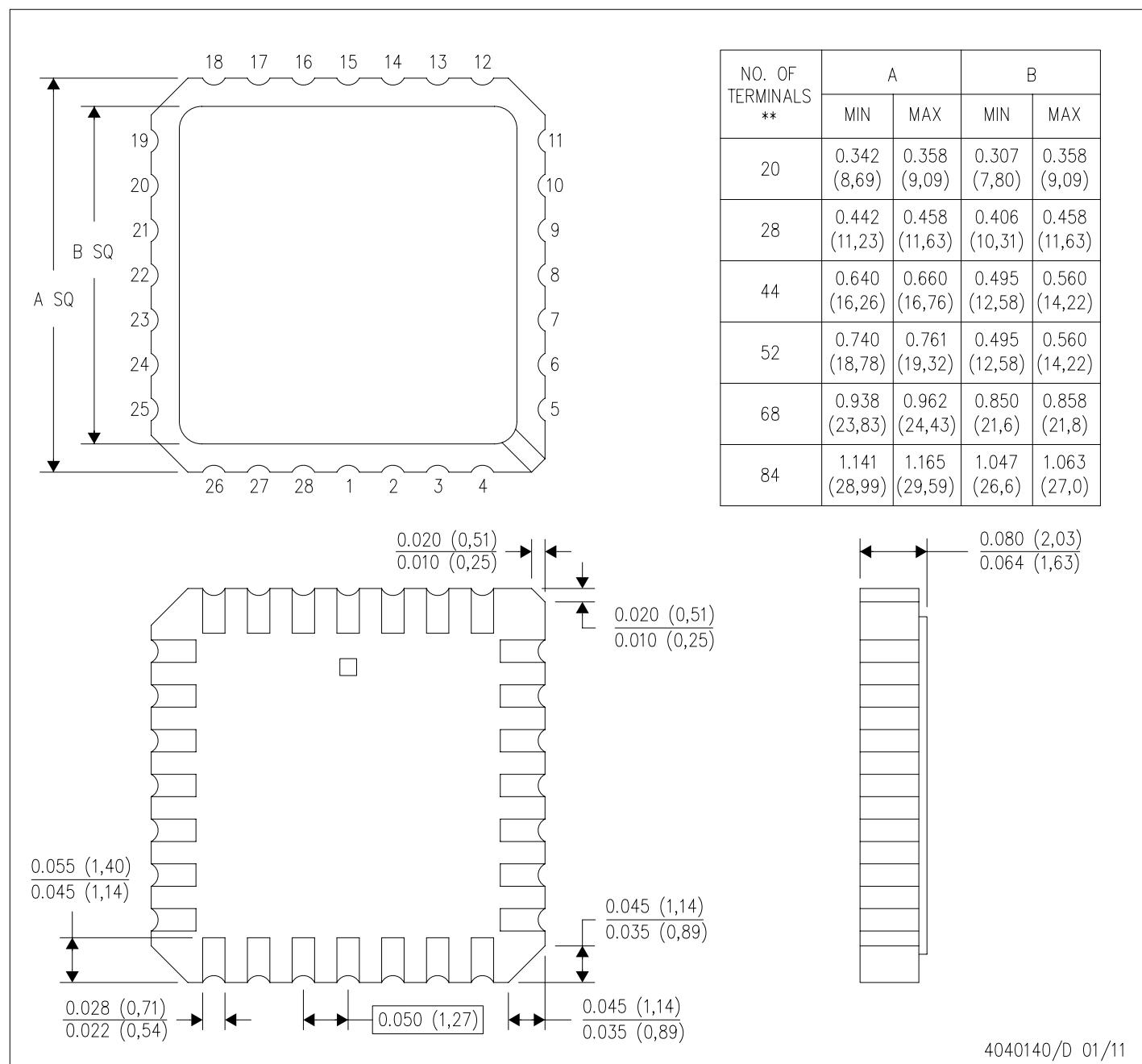
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC174DR	SOIC	D	16	2500	364.0	364.0	27.0
SN74HC174DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC174DRG4	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC174NSR	SO	NS	16	2000	367.0	367.0	38.0
SN74HC174PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74HC174PWR	TSSOP	PW	16	2000	366.0	364.0	50.0
SN74HC174PWRG4	TSSOP	PW	16	2000	367.0	367.0	35.0

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004

4040140/D 01/11

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

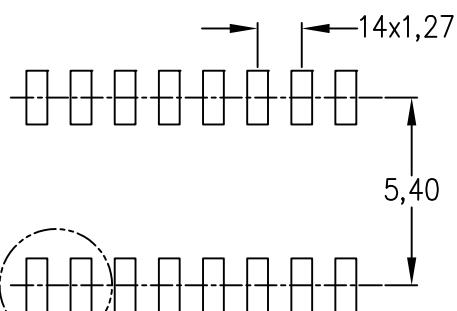
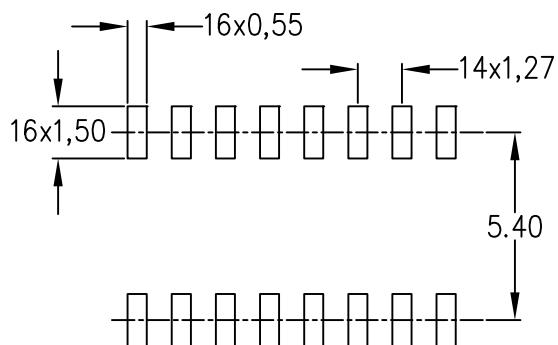
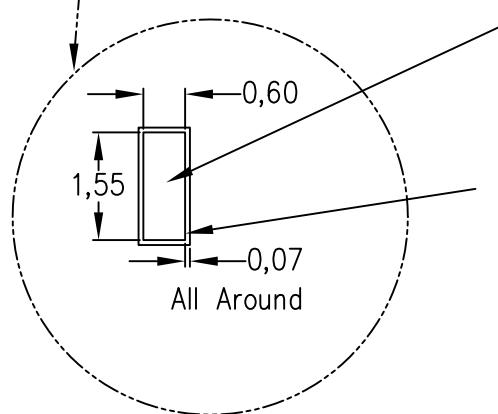
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.

D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.

E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)Stencil Openings
(Note D)Example
Non Soldermask Defined PadExample
Pad Geometry
(See Note C)Example
Solder Mask Opening
(See Note E)

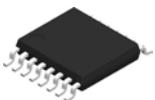
4211283-4/E 08/12

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

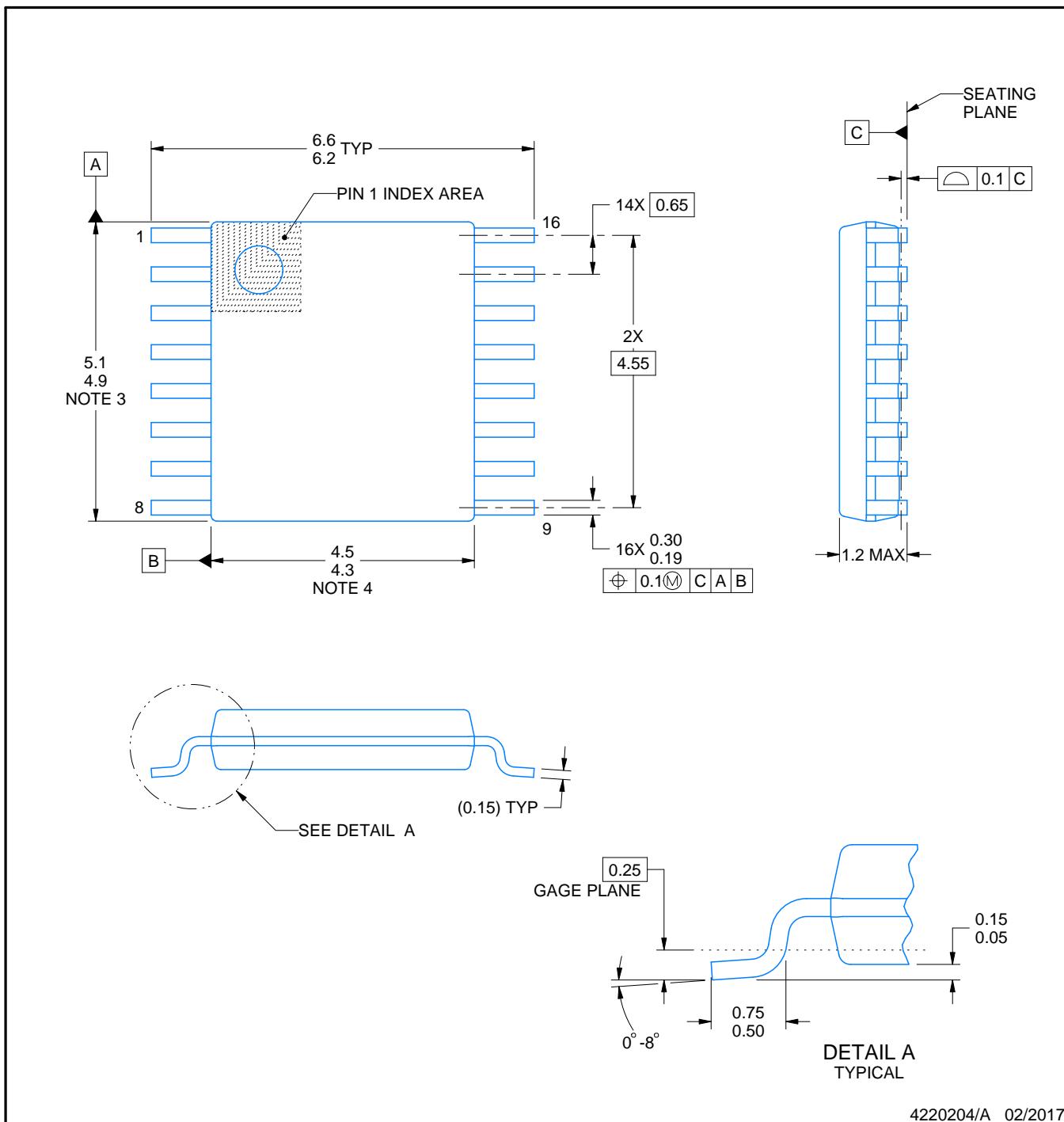
PACKAGE OUTLINE

PW0016A



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

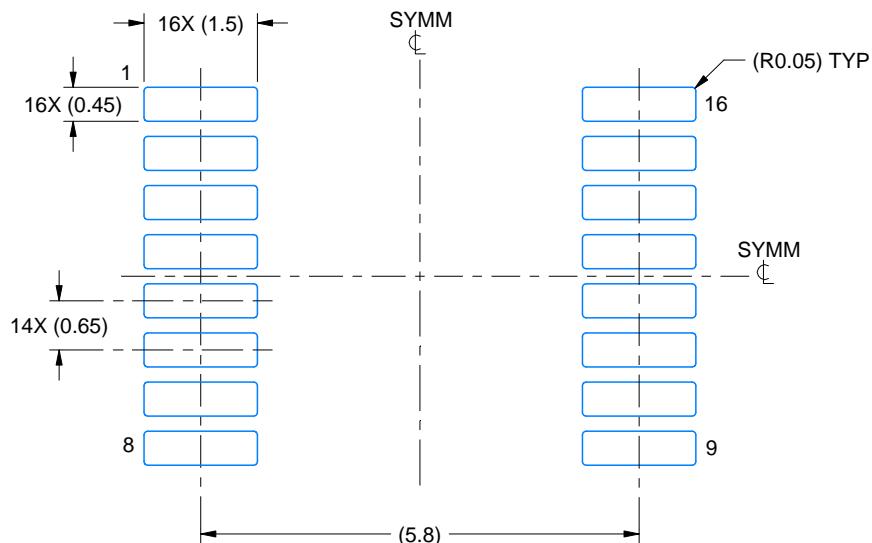
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

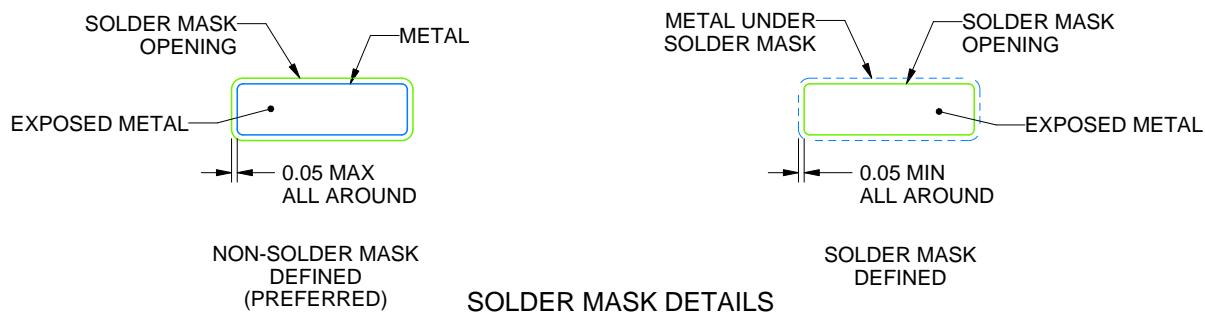
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220204/A 02/2017

NOTES: (continued)

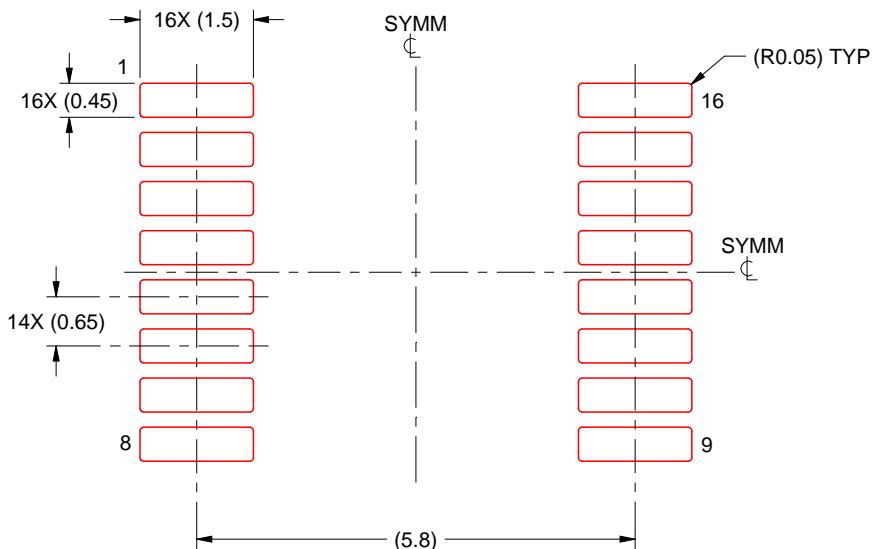
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/A 02/2017

NOTES: (continued)

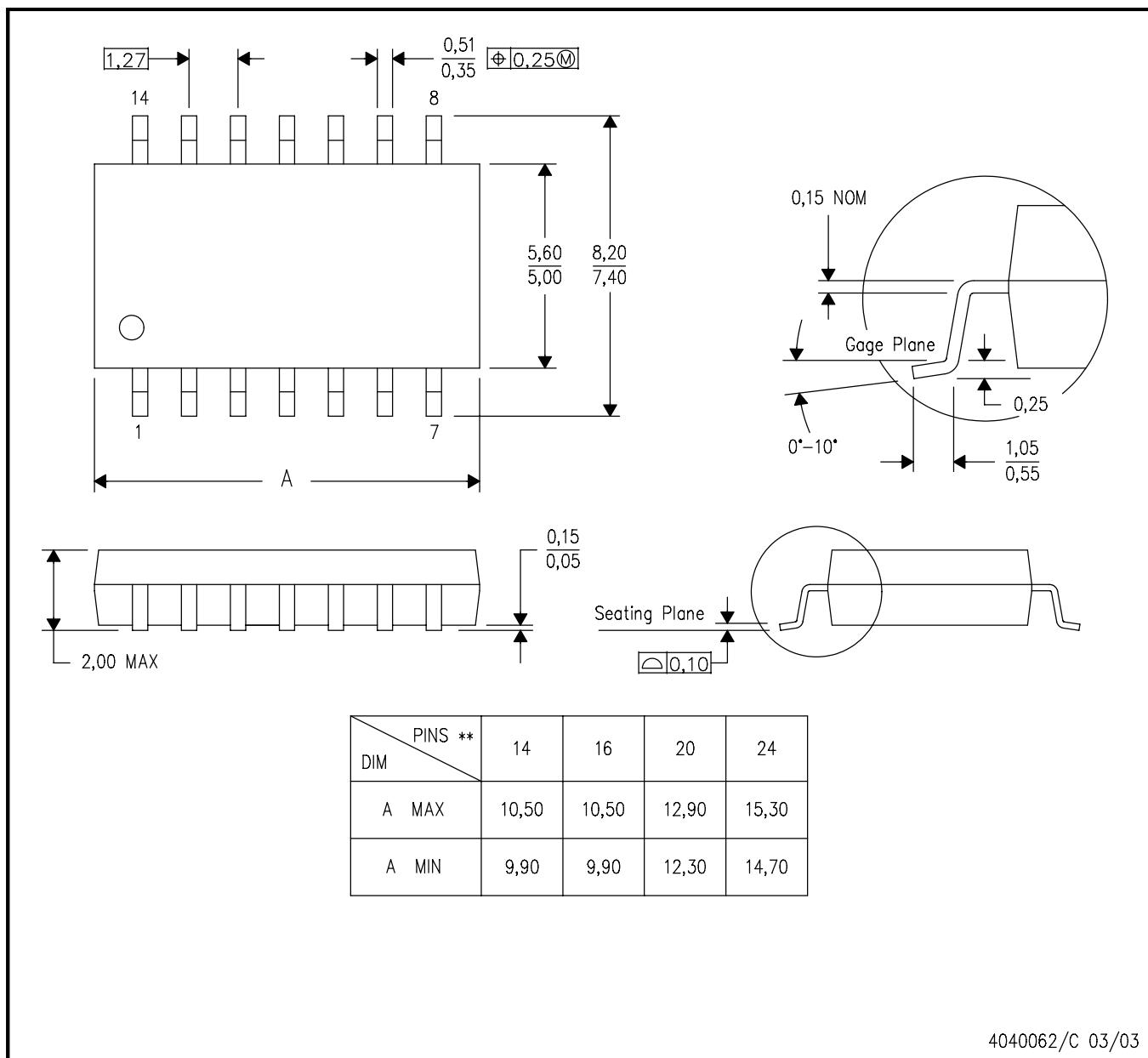
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE

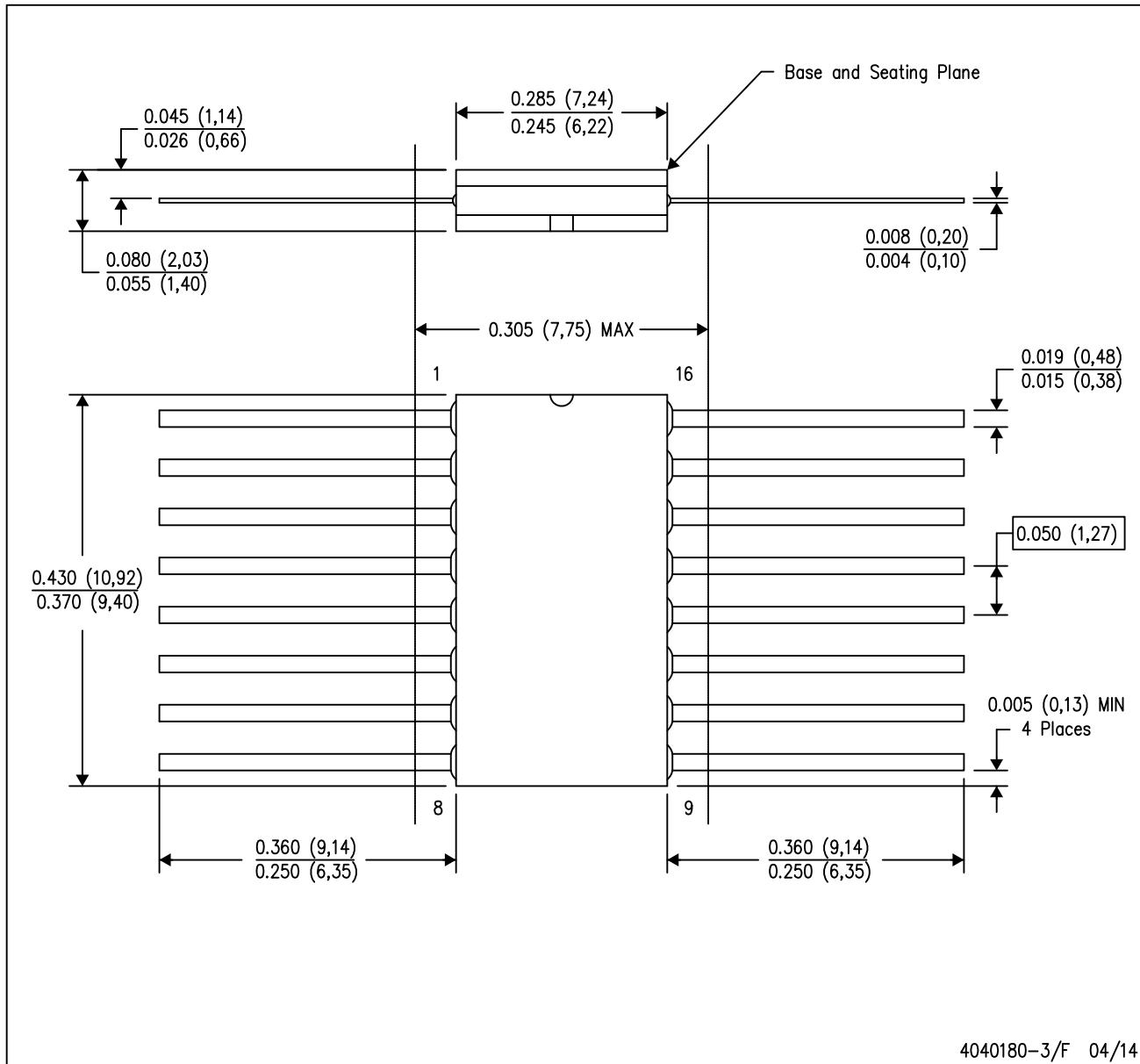


4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



4040180-3/F 04/14

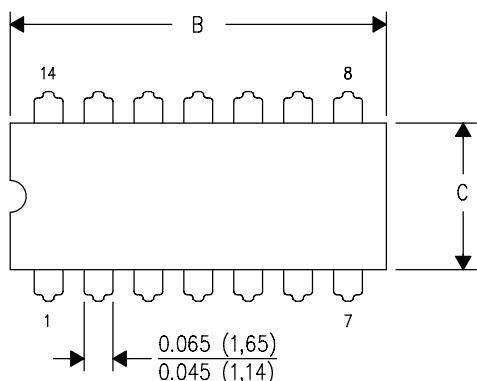
NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL-STD 1835 GDFP2-F16

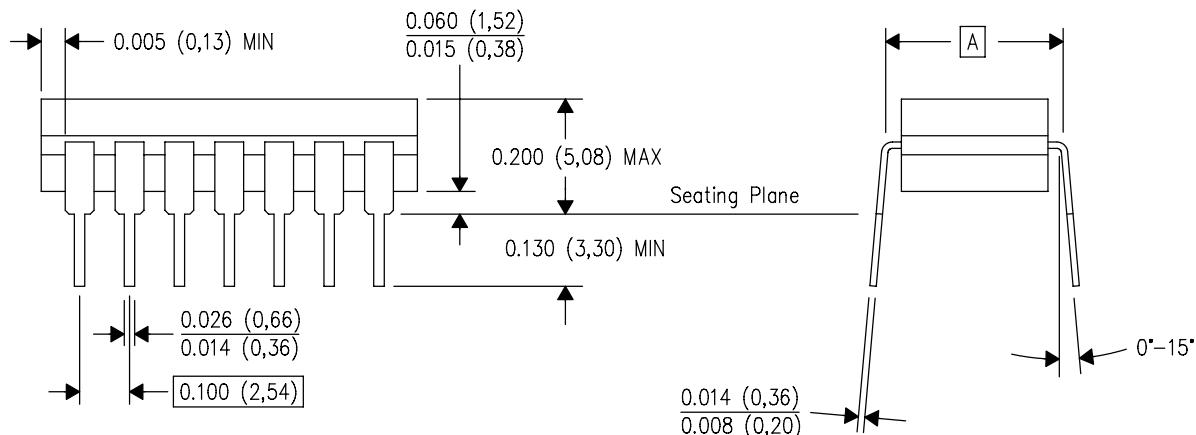
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



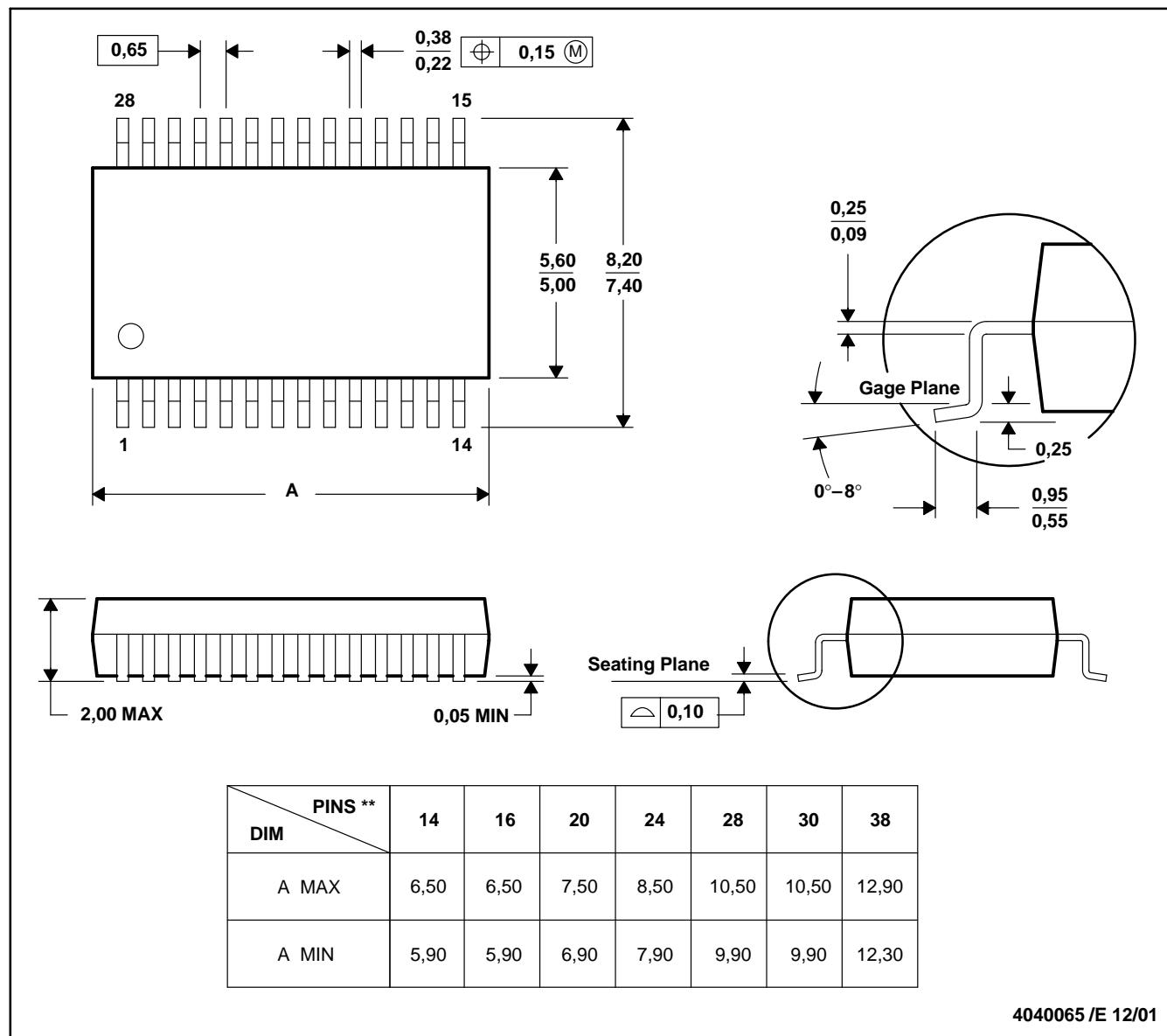
4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



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